

MOS FIELD EFFECT TRANSISTOR

NP82N10CLD, NP82N10DLD, NP82N10ELD

SWITCHING

N-CHANNEL POWER MOS FET

INDUSTRIAL USE

DESCRIPTION

These products are N-channel MOS Field Effect Transistor designed for high current switching applications.

FEATURES

- Channel temperature 175 degree rated
- Super low on-state resistance
 $R_{DS(on)1} = 20 \text{ m}\Omega \text{ MAX. (} V_{GS} = 10 \text{ V, } I_D = 41 \text{ A)}$
- ★ $R_{DS(on)2} = 26 \text{ m}\Omega \text{ MAX. (} V_{GS} = 5 \text{ V, } I_D = 41 \text{ A)}$
- ★ • Low C_{iss} : $C_{iss} = 4930 \text{ pF TYP.}$
- Built-in gate protection diode

ORDERING INFORMATION

PART NUMBER	PACKAGE
NP82N10CLD	TO-220AB
NP82N10DLD	TO-262
NP82N10ELD	TO-263

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$)

Drain to Source Voltage	V_{DSS}	100	V
Gate to Source Voltage	V_{GSS}	± 20	V
Drain Current (DC) ^{Note1}	$I_{D(DC)}$	± 82	A
Drain Current (Pulse) ^{Note2}	$I_{D(pulse)}$	± 328	A
Total Power Dissipation ($T_A = 25^\circ\text{C}$)	P_T	1.8	W
Total Power Dissipation ($T_C = 25^\circ\text{C}$)	P_T	185	W
★ Single Avalanche Current ^{Note3}	I_{AS}	82 / 50 / 12	A
★ Single Avalanche Energy ^{Note3}	E_{AS}	6.7 / 250 / 720	mJ
Channel Temperature	T_{ch}	175	$^\circ\text{C}$
Storage Temperature	T_{stg}	-55 to +175	$^\circ\text{C}$

Notes 1. Package Limit = $\pm 75 \text{ A}$

2. $PW \leq 10 \text{ }\mu\text{s}$, Duty cycle $\leq 1 \%$

3. Starting $T_{ch} = 25^\circ\text{C}$, $R_G = 25 \text{ }\Omega$, $V_{GS} = 20 \text{ V} \rightarrow 0 \text{ V}$

THERMAL RESISTANCE

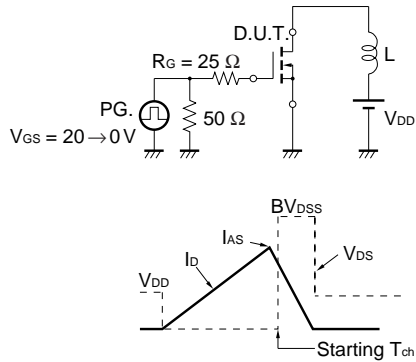
Channel to Case	$R_{th(ch-C)}$	0.81	$^\circ\text{C/W}$
Channel to Ambient	$R_{th(ch-A)}$	83.3	$^\circ\text{C/W}$

The information contained in this document is being issued in advance of the production cycle for the device. The parameters for the device may change before final production or NEC Corporation, at its own discretion, may withdraw the device prior to its production.
 Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

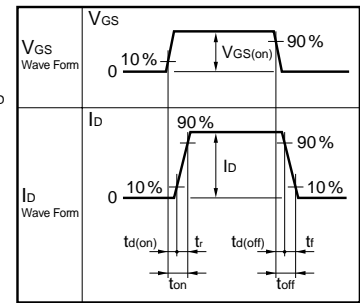
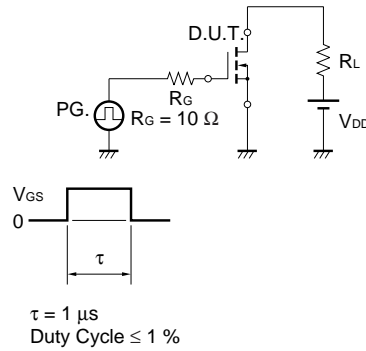
★ ELECTRICAL CHARACTERISTICS (T_A = 25 °C)

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain to Source On-state Resistance	R _{DS(on)1}	V _{GS} = 10 V, I _D = 41 A		14	20	mΩ
	R _{DS(on)2}	V _{GS} = 5 V, I _D = 41 A		18	26	mΩ
	R _{DS(on)3}	V _{GS} = 4.5 V, I _D = 41 A		20	28	mΩ
Gate to Source Cut-off Voltage	V _{GS(off)}	V _{DS} = 10 V, I _D = 250 μA	1.5	2.0	2.5	V
Forward Transfer Admittance	y _{fs}	V _{DS} = 10 V, I _D = 41 A	25	50		S
Drain Leakage Current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V			10	μA
Gate to Source Leakage Current	I _{GSS}	V _{GS} = ±20 V, V _{DS} = 0 V			±10	μA
Input Capacitance	C _{iss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz		4930	7400	pF
Output Capacitance	C _{oss}			990	870	pF
Reverse Transfer Capacitance	C _{rss}			580	130	pF
Turn-on Delay Time	t _{d(on)}	I _D = 41 A, V _{GS(on)} = 10 V, V _{DD} = 50 V, R _G = 10 Ω		60	130	ns
Rise Time	t _r			390	980	ns
Turn-off Delay Time	t _{d(off)}			340	680	ns
Fall Time	t _f			370	940	ns
Total Gate Charge	Q _{G1}	I _D = 82 A, V _{DD} = 80 V, V _{GS} = 5 V		69	105	nC
	Q _{G2}	I _D = 82 A, V _{DD} = 80 V, V _{GS} = 10 V		130	190	nC
Gate to Source Charge	Q _{GS}			18		nC
Gate to Drain Charge	Q _{GD}			48		nC
Body Diode Forward Voltage	V _{F(S-D)}	I _F = 82 A, V _{GS} = 0 V		1.0		V
Reverse Recovery Time	t _{rr}	I _F = 82 A, V _{GS} = 0 V, di/dt = 100A/μs		170		ns
Reverse Recovery Charge	Q _{rr}			920		nC

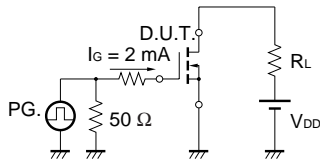
TEST CIRCUIT 1 AVALANCHE CAPABILITY



TEST CIRCUIT 2 SWITCHING TIME

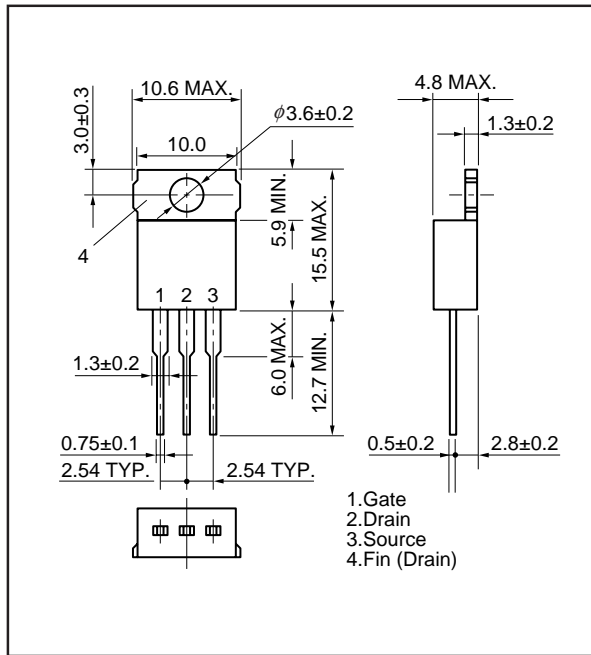


TEST CIRCUIT 3 GATE CHARGE

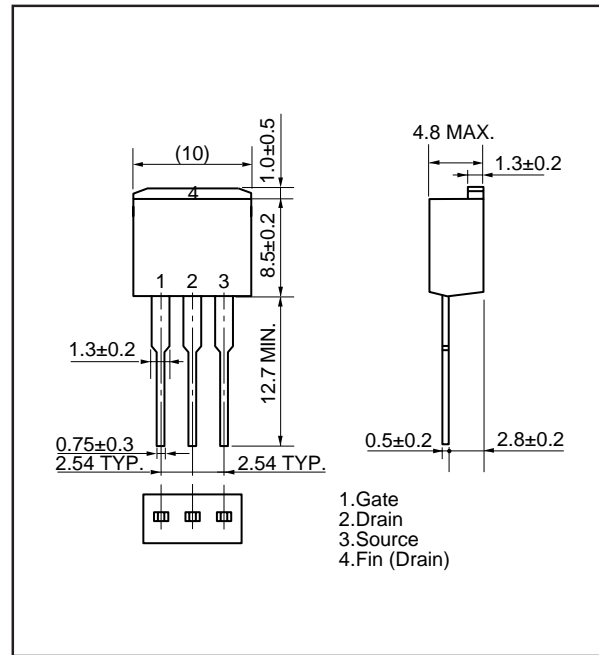


PACKAGE DRAWINGS (Unit: mm)

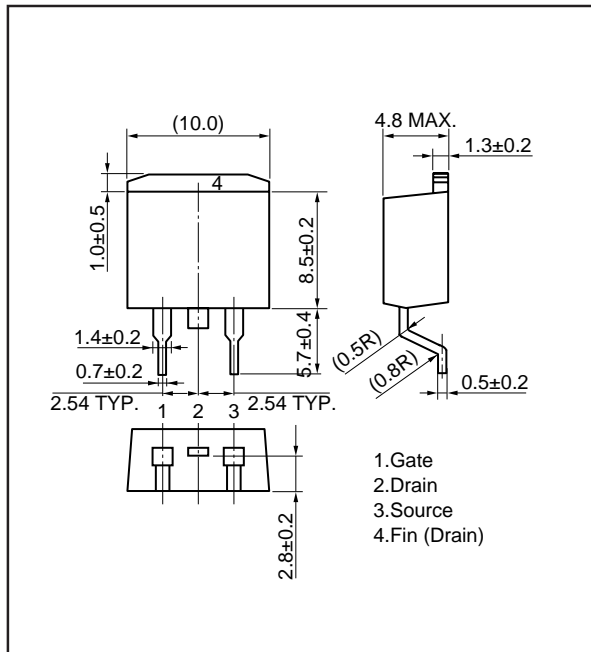
1) TO-220AB (MP-25)



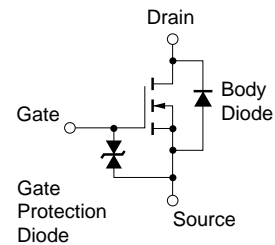
2) TO-262 (MP-25 Fin Cut)



3) TO-263 (MP-25ZJ)



EQUIVALENT CIRCUIT



Remark The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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